

Symbol	Control Dimensions in millimetres			Altern. Dimensions in inches		
	MIN	Nominal	MAX	MIN	Nominal	MAX
A	1.70		2.00	0.067		0.079
A1	0.05		0.20	0.002		0.008
A2	1.65		1.85	0.065		0.073
D	6.90		7.50	0.272		0.295
E	7.40		8.20	0.291		0.323
E1	5.00		5.60	0.197		0.220
L	0.55		0.95	0.022		0.037
e	0.65 BSC.			0.026 BSC.		
b	0.22		0.38	0.009		0.015
c	0.09		0.25	0.004		0.010
θ	0°		8°	0°		8°
Pin features						
N	20					
Conforms to JEDEC MO-150 AE Iss. B						

This drawing supersedes: -
418/ED/51481/002 (Swindon/Plymouth)

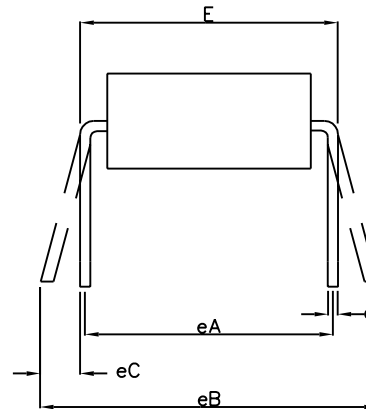
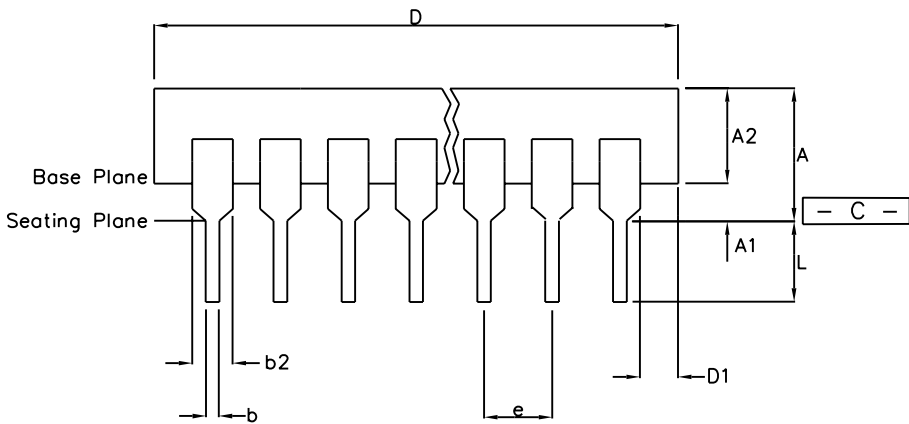
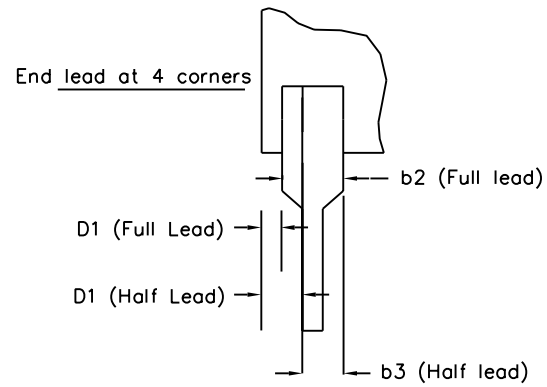
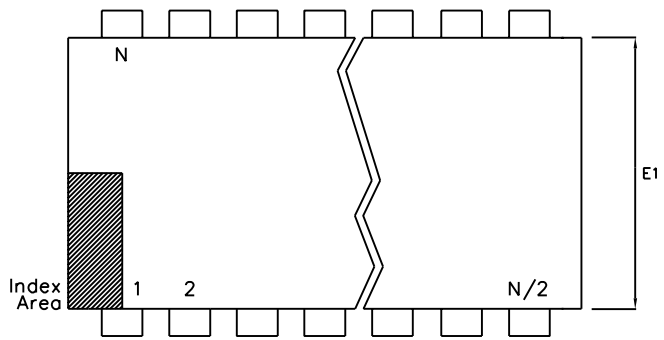
Notes:

1. A visual index feature, e.g. a dot, must be located within the cross-hatched area.
2. Controlling dimension are in millimeters.
3. Dimensions D and E1 do not include mould flash or protusion. Mould flash or protusion shall not exceed 0.20 mm per side. D and E1 are maximum plastic body size dimensions including mould mismatch.
4. Dimension b does not include dambar protusion/intrusion. Allowable dambar protusion shall be 0.13 mm total in excess of b dimension. Dambar intrusion shall not reduce dimension b by more than 0.07 mm.

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		Package Code	DD
Previous package codes		Package Outline for 20 lead SSOP (5.3mm Body Width)	
NP / N			
		GPD00294	



	Min mm	Max mm	Min Inches	Max Inches
A		5.33		0.210
A1	0.38		0.015	
A2	2.92	4.95	0.115	0.195
b	0.36	0.56	0.014	0.022
b2	1.14	1.78	0.045	0.070
b3	n/a	n/a	n/a	n/a
c	0.20	0.36	0.008	0.014
D	22.35	23.37	0.880	0.920
D1	0.13		0.005	
E	7.62	8.26	0.300	0.325
E1	6.10	7.11	0.240	0.280
e	2.54 BSC		0.100 BSC	
eA	7.62 BSC		0.300 BSC	
eB		10.92		0.430
eC	0.00	1.52	0.000	0.060
L	2.92	3.81	0.115	0.150
N		18		18
Conforms to JEDEC MS-001AC Issue D				

Notes:

1. Leadframe Material: Copper
2. Leadframe finish: Solder Plate
3. Dimensions D, D1 & E1 do not include mould flash or protrusions.
4. Dimensions E & eA are measured with leads constrained to be perpendicular to datum --- C ---
5. Dimensions eB & eC are measured with the leads unconstrained
6. Controlling dimensions are Inches. Millimeter conversions are not necessarily exact.
7. N is the maximum of terminal positions.

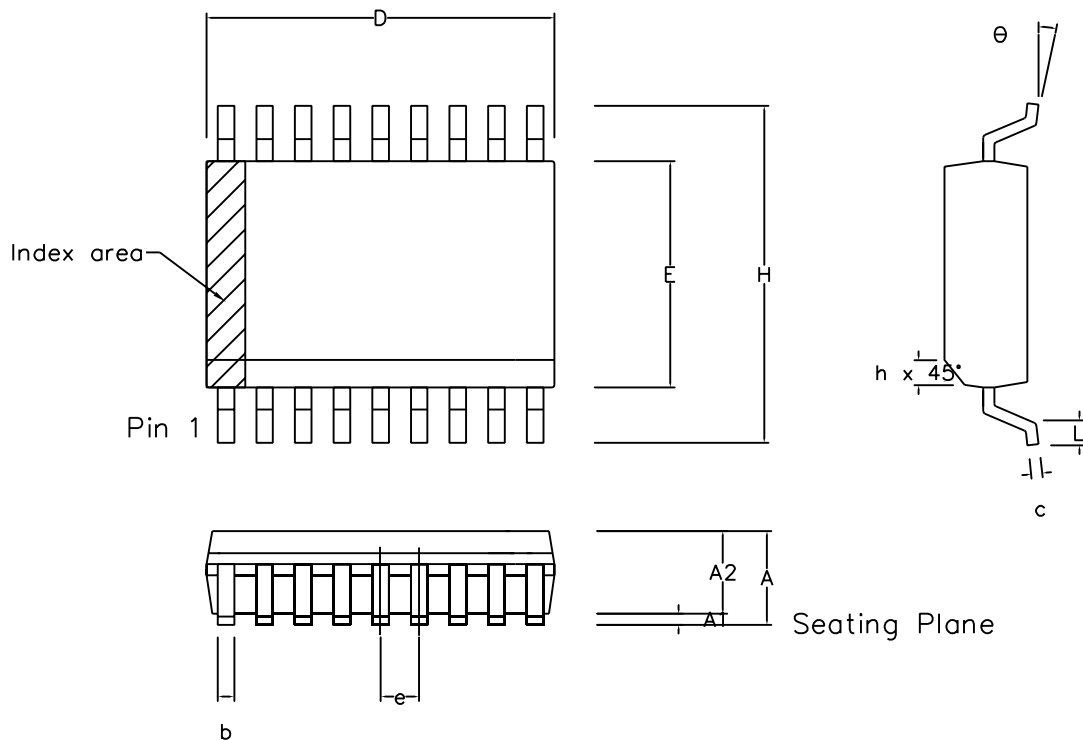
This drawing supersedes: -
Plymouth/Swindon drawing # 418/ED/39502/004

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Previous package codes	DP / E
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Package Code	DA
Package Outline for 18 Lead PDIP	
GPD00348	



Symbol	Control Dimensions in millimetres			Altern. Dimensions in inches		
	MIN	Nominal	MAX	MIN	Nominal	MAX
A	2.35		2.65	0.093		0.104
A1	0.10		0.30	0.004		0.012
A2	2.25		2.35	0.089		0.092
D	11.35		11.75	0.447		0.463
H	10.00		10.65	0.394		0.419
E	7.40		7.60	0.291		0.299
L	0.40		1.27	0.016		0.050
e	1.27 BSC.			0.050 BSC.		
b	0.33		0.51	0.013		0.020
c	0.23		0.32	0.009		0.013
θ	0°		8°	0°		8°
h	0.25		0.75	0.010		0.029
Pin features						
N	18					
Conforms to JEDEC MS-013AB Iss. C						

Notes:

1. The chamfer on the body is optional. If not present, a visual index feature, e.g. a dot, must be located within the cross-hatched area.
2. Controlling dimensions are in millimeters
3. Dimension D do not include mould flash, protusion or gate burrs. These shall not exceed 0.006" per side.
4. Dimension E1 do not include inter-lead flash or protusion. These shall not exceed 0.010" per side.
5. Dimension b does not include dambar protusion / intrusion. Allowable dambar protusion shall be 0.004" total in excess of b dimension.

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		Package Code	DC
Previous package codes		Package Outline for 18 lead SOIC (0.300" Body Width)	
MP / S			
		GPD00014	